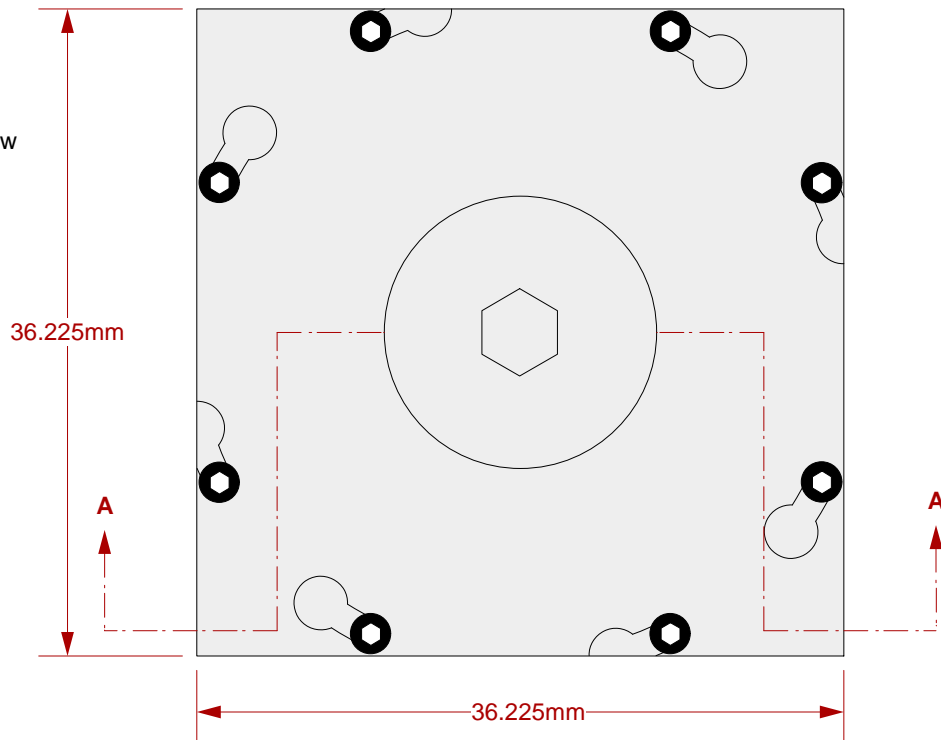


GHz BGA Socket - Direct mount, solderless

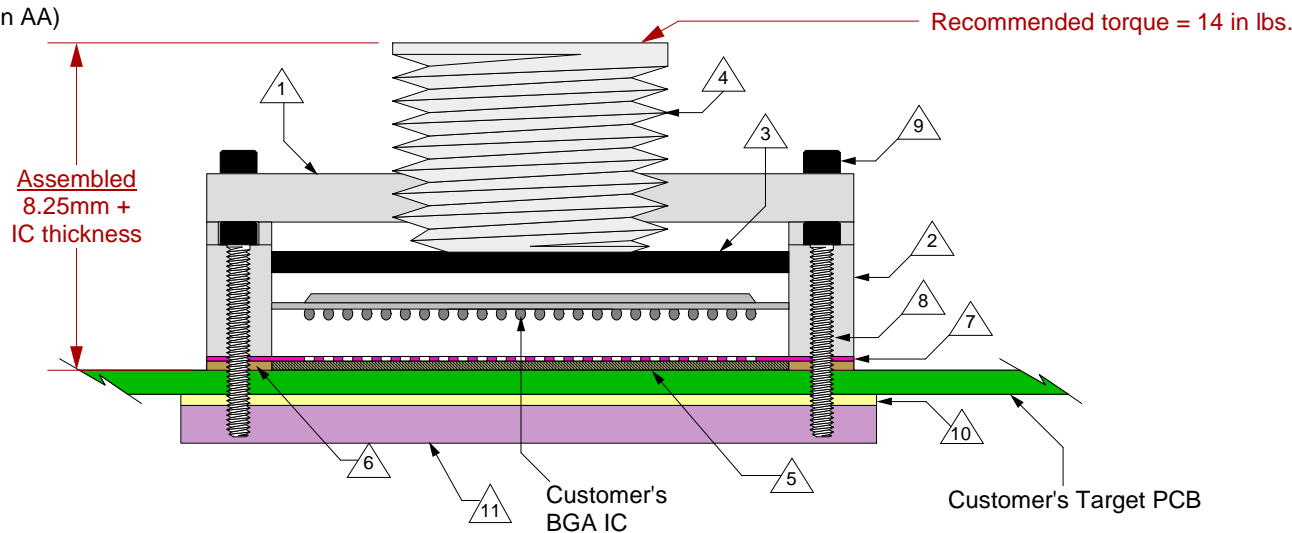
Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

Top View



Side View
(Section AA)



- | | |
|----|--|
| 1 | Socket Lid: Black anodized Aluminum.
Thickness = 2.5mm. |
| 2 | Socket base: Black anodized Aluminum.
Thickness = 5mm. |
| 3 | Compression Plate: Black anodized Aluminum.
Thickness = 2.5mm. |
| 4 | Compression screw: Clear anodized Aluminum.
Thickness = 5mm, Hex socket = 5mm. |
| 5 | Elastomer: 40 micron dia gold plated brass
filaments arranged symmetrically in a silicone
rubber (63.5 degree angle).
Thickness = 0.75mm. |
| 6 | Elastomer Guide: Cirlex or equivalent
Thickness = 0.725mm. |
| 7 | Ball Guide: Kapton polyimide. |
| 8 | Socket base screw: Socket head cap, Alloy steel with
black oxide finish, 0-80 fine thread, 9.525mm long. |
| 9 | Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine
thread. |
| 10 | Insulation Plate: FR4/G10, 1.59mm thick. |
| 11 | Backing Plate: Black anodized Aluminum, Thickness
= 6.35mm. |

SG-BGA-6011 Drawing

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11351 Rupp Drive, Suite 400, Burnsville, MN 55337
Tele: (952) 229-8200
www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: G

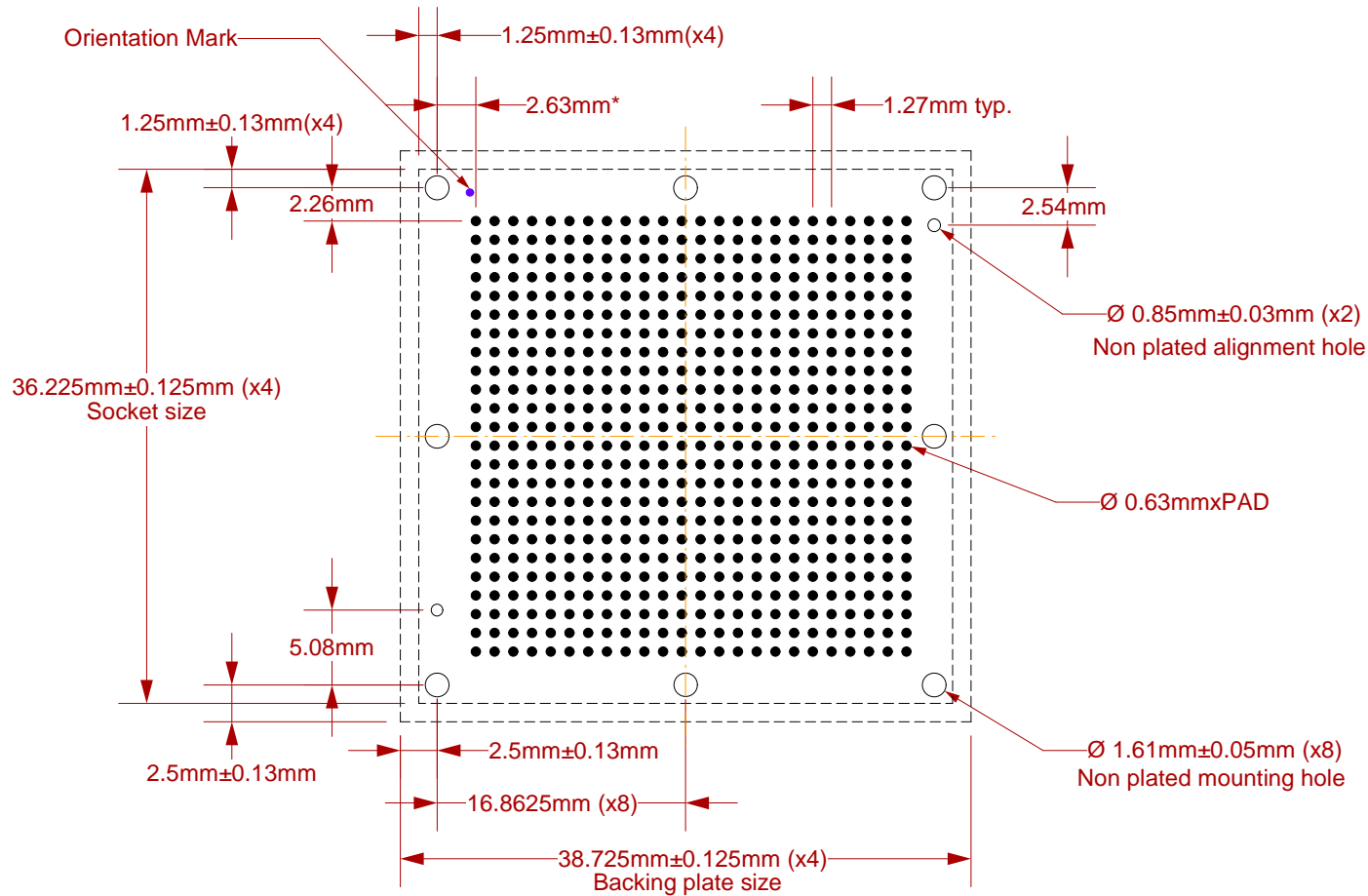
Drawing: Meghann Fedde

Date: 8/17/01

File: SG-BGA-6011 Dwg

Modified: 7/16/09, AE

All tolerances: ± 0.125 mm (unless stated otherwise). Materials and specifications are subject to change without notice.



Target PCB Recommendations


Total thickness: 2.4mm min.

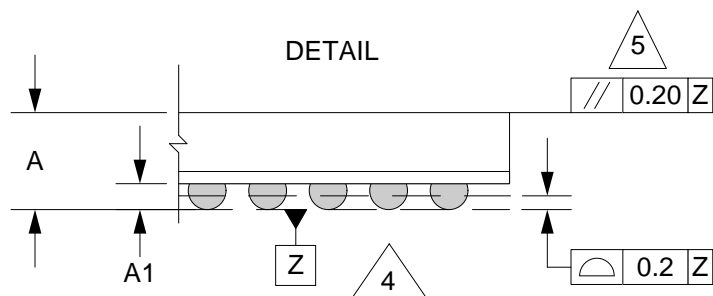
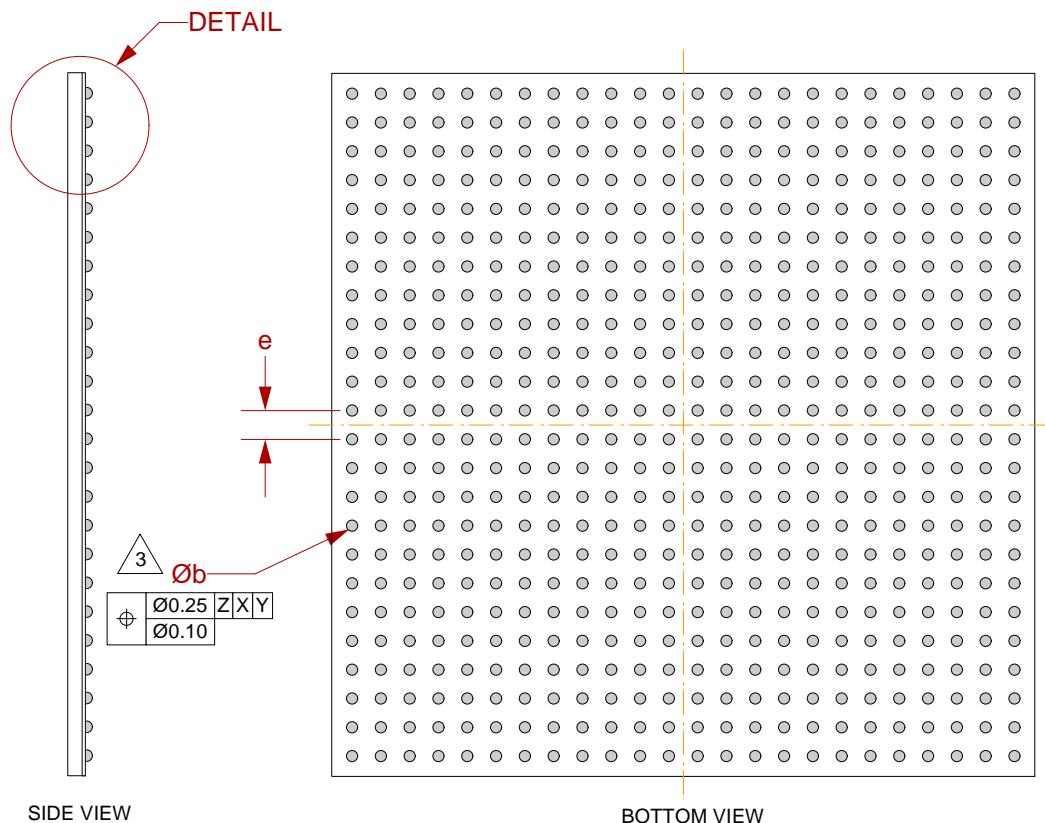
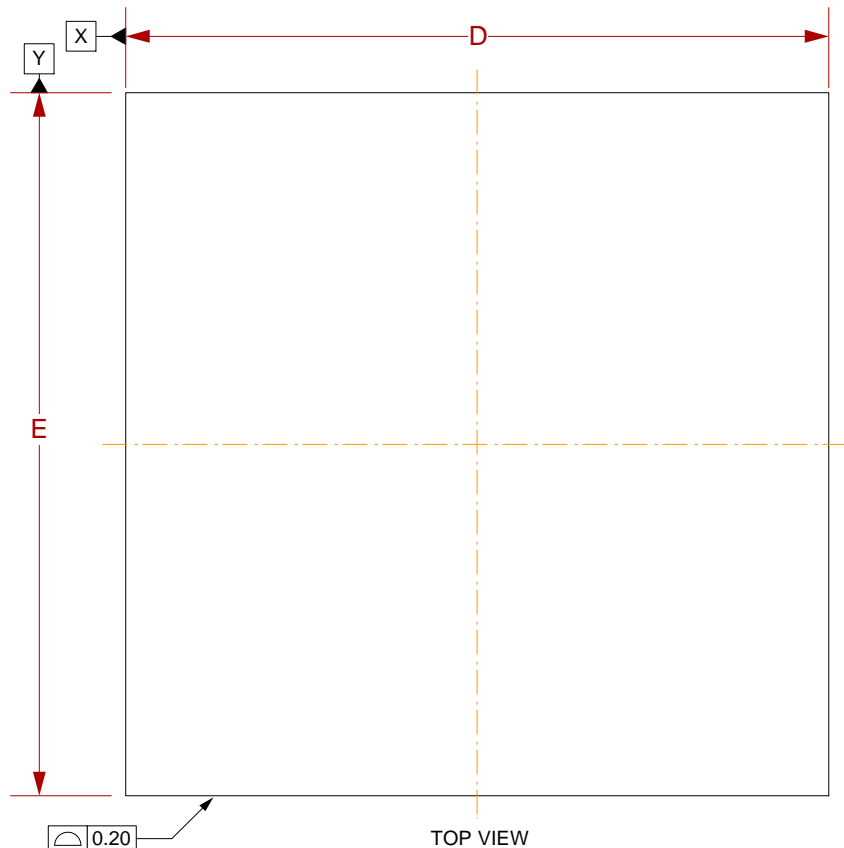
Plating: Gold or Solder finish

PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.


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	<p>Drawing: Meghann Fedde</p>	<p>Date: 8/17/01</p>	<p>File: SG-BGA-6011 Dwg</p>	<p>Modified: 7/16/09, AE</p>



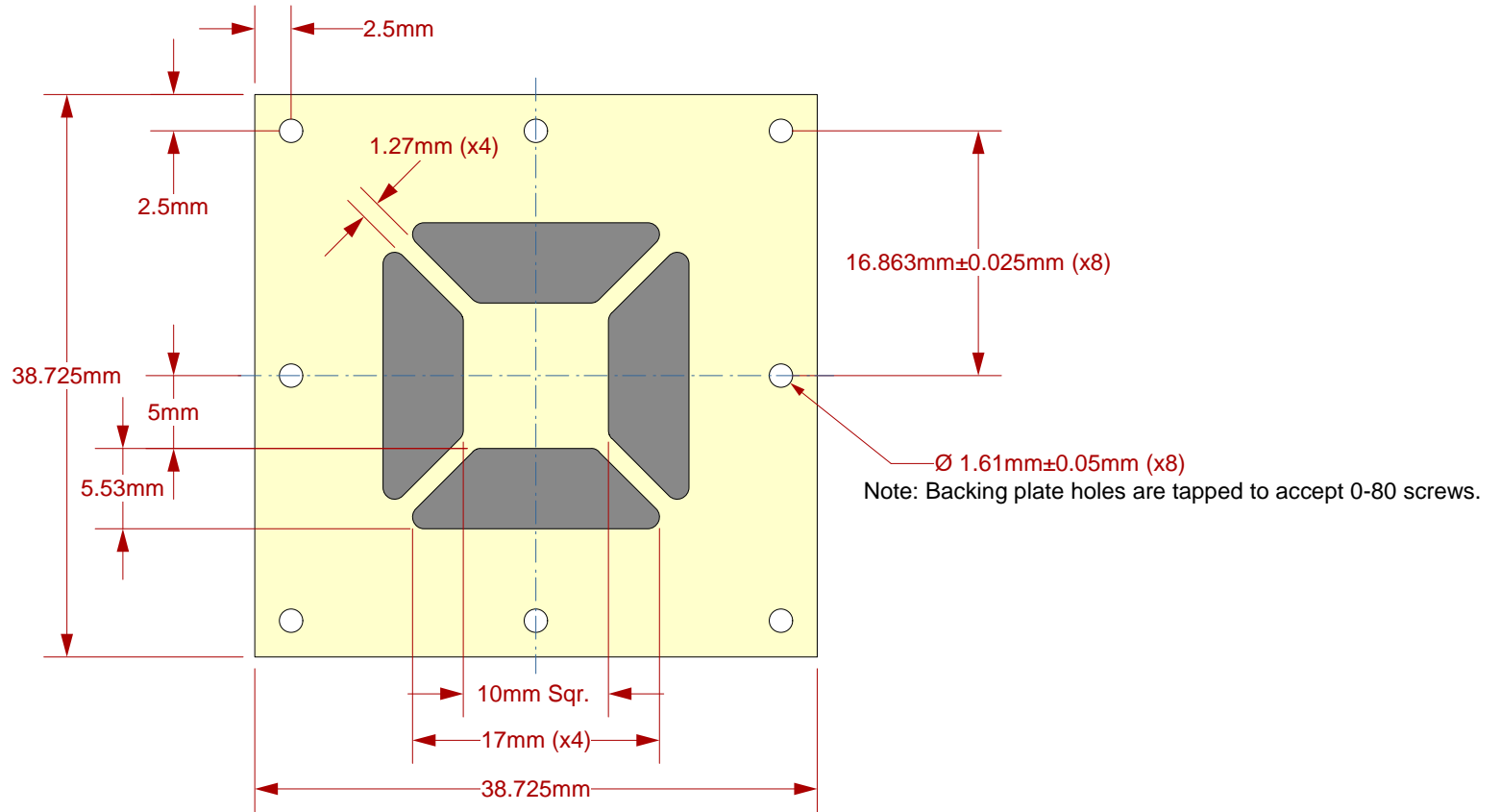
- 1 Dimensions are in millimeters.
- 2 Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5 Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.5
A1	0.5	0.7
b		0.90
D	31.00 BSC	
E	31.00 BSC	
e	1.27 BSC	

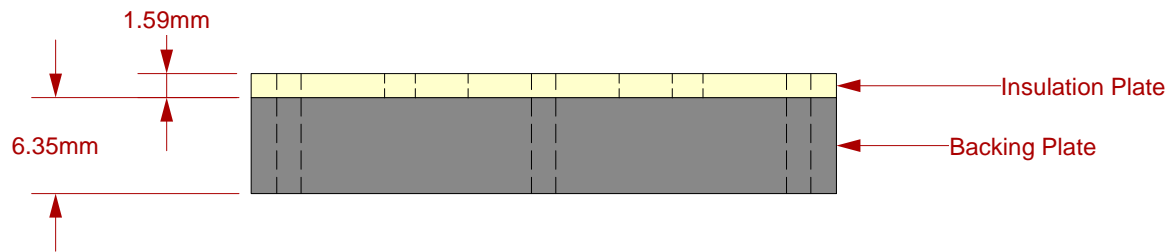
Array 24x24

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	<p>Drawing: Meghann Fedde</p>		<p>Date: 8/17/01</p>		
	<p>File: SG-BGA-6011 Dwg</p>		<p>Modified: 7/16/09, AE</p>		


Top View



Side View



Description: Insulation Plate and Backing Plate

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		Drawing: Meghann Fedde	Date: 8/17/01	
		File: SG-BGA-6011 Dwg	Modified: 7/16/09, AE	

All dimensions are in mm.
 All tolerances are +/- 0.125mm.
 (Unless stated otherwise)